

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L2	11	("20020058397" "20030008518" "20030104320" "20030194877" "20040060579" "5643407" "5798323" "6100183" "6107202" "6417108" "6713402"). PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/25 14:21
L3	2194	pattern\$4 and (trench\$1 via\$1) and "low-k" and (solvent\$1 acid\$1 (dimethyl same acetamide\$1) dmac) and (plasma non-plasma) and (dielectric\$1 osg organosilicate\$1 msq methylsilsesquioxane\$1 fsg fluor\$3 "silicate glass" sio2 (silicon same dioxide\$1))	US-PGPUB; USPAT	OR	ON	2008/08/25 14:22
L4	136	L3 and "134".das.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/25 14:22
L5	96	L4 and 134/1,1.2.2.3,19,26,16,21,34,35,37.cds.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/25 14:22
L6	79	L5 and photoresist\$1	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/25 14:22
L7	79	L6 and plasma	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/25 14:22
L8	36	L7 and (anneal\$4 bak\$4)	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/25 14:22
L9	11	pattern\$4 and (trench\$1 via\$1) and "low-k" and (solvent\$1 acid\$1 (dimethyl same acetamide\$1) dmac) and (plasma non-plasma) and (dielectric\$1 osg organosilicate\$1 msq methylsilsesquioxane\$1 fsg fluor\$3 "silicate glass" sio2 (silicon same dioxide\$1))	FPRS; EPO; JPO; DERWENT	OR	ON	2008/08/25 14:22
L10	47	L8 L9	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2008/08/25 14:22
L11	58	2 10	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2008/08/25 14:24
L12	11	11 and (wet near3 (clean\$4 strip\$4)) same (dry near3 (clean\$4 strip\$4))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2008/08/25 14:25
L13	2	"6554912".pn.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2008/08/25 15:34
L14	2	13 and (h2 hydrogen o2 oxygen inert n2 nitrogen)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2008/08/25 15:35

L15	1	13 and plasma same (h2 hydrogen o2 oxygen inert n2 nitrogen)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2008/08/25 15:36
L16	2	"5643407".pn.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2008/08/25 15:49
L17	4	13 16	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2008/08/25 15:49
L18	2	17 and (copper cu)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2008/08/25 15:49
L19	3	17 and deposit\$4	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2008/08/25 15:52
L20	27	11 and (copper cu cuprous) same deposit\$4	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2008/08/25 16:07
L21	11	20 and (copper cu cuprous) near3 deposit\$4	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2008/08/25 16:08
L22	2	17 and (dielectric\$1 org organosilicate\$1 msq methylsilsequioxane\$1 fsg fluor\$3 "silicate glass" sio2 (silicon same dioxide\$1))	US-PGPUB; USPAT	OR	ON	2008/08/25 16:29
L23	1	17 and (dmac (dimethyl same acetamide\$1))	US-PGPUB; USPAT	OR	ON	2008/08/25 16:57
L24	1	17 and acid\$2	US-PGPUB; USPAT	OR	ON	2008/08/25 17:00
L25	1	17 and (critical dimension\$1 extru\$5)	US-PGPUB; USPAT	OR	ON	2008/08/25 17:21
L26	36	L7 and (anneal\$4 bak\$4)	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/25 17:22
L27	1	7 and ((critical same dimension\$1) extru\$5)	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/25 17:23
L28	1	27 and ((critical same dimension\$1) extru\$5) same (anneal\$4 bak\$3)	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/25 17:26
L29	69	wafer\$1 and ((critical same dimension\$1) (metal\$3 same extru\$5)) same (anneal\$4 bak\$3)	US-PGPUB; USPAT	OR	ON	2008/08/25 17:27
L30	820	wafer\$1 and ((critical same dimension\$1) (metal\$3 same extru\$5)) same (anneal\$4 bak\$3)	US-PGPUB; USPAT	OR	ON	2008/08/25 17:28
L31	322	30 and wafer\$1 same ((critical same dimension\$1) (metal\$3 same extru\$5)) same (anneal\$4 bak\$3)	US-PGPUB; USPAT	OR	ON	2008/08/25 17:28

L32	1	31 and wafer\$1 same ((critical same dimension\$1) and (metal\$3 same extru\$5)) same (anneal\$4 bak\$3)	US-PGPUB; USPAT	OR	ON	2008/08/25 17:28
L33	1	31 and wafer\$1 and ((critical same dimension\$1) and (metal\$3 same extru\$5)) same (anneal\$4 bak\$3)	US-PGPUB; USPAT	OR	ON	2008/08/25 17:28
L34	8	((critical same dimension\$1) and (metal\$3 same extru\$5)) same (anneal\$4 bak\$3)	US-PGPUB; USPAT	OR	ON	2008/08/25 17:29
L35	2	"6417108".pn.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2008/08/25 17:42
L36	0	35 and (dmac (dimethyl same acetamide\$1))	US-PGPUB; USPAT	OR	ON	2008/08/25 17:47
S1	1	"20050045206".pn.	US-PGPUB	OR	ON	2008/08/15 10:39
S2	6	("5643407" "20030104320" "20030008518" "6107202" "6417108" "20020058397").pn.	US-PGPUB; USPAT	OR	ON	2008/08/15 10:41
S3	1	S1 and anneal	US-PGPUB	OR	ON	2008/08/15 11:14
S4	1	S1 and minutes	US-PGPUB	OR	ON	2008/08/15 11:39
S5	1	"5643407".pn.	USPAT	OR	ON	2008/08/15 11:41
S6	1	S5 and (minute\$1 seconds)	USPAT	OR	ON	2008/08/15 11:42
S7	1	S1 and solvent	US-PGPUB	OR	ON	2008/08/15 12:17
S8	0	S1 and (moistur\$5 water aqueous)	US-PGPUB	OR	ON	2008/08/15 12:19
S9	1	S1 and component\$1	US-PGPUB	OR	ON	2008/08/15 12:19
S10	0	S1 and (moistur\$5 water aqueous vapor\$7)	US-PGPUB	OR	ON	2008/08/15 12:23
S11	1	S6 and (moistur\$5 water aqueous vapor\$7)	USPAT	OR	ON	2008/08/15 12:23
S12	1	"20050045206".pn.	US-PGPUB	OR	ON	2008/08/21 15:57
S13	1	S12 and clean\$4	US-PGPUB	OR	ON	2008/08/21 15:57
S14	6	("5643407" "20030104320" "20030008518" "6107202" "6417108" "20020058397").pn.	US-PGPUB; USPAT	OR	ON	2008/08/21 15:58
S15	4	S14 and clean\$4	US-PGPUB; USPAT	OR	ON	2008/08/21 15:58
S16	0	S12 and embodi\$5	US-PGPUB	OR	ON	2008/08/21 16:52
S17	11	("20020058397" "20030008518" "20030104320" "20030194877" "20040060579" "5643407" "5798323" "6100183" "6107202" "6417108" "6713402").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/25 10:55

S18	2194	pattern\$4 and (trench\$1 via\$1) and "low-k" and (solvent\$1 acid\$1 (dimethyl same acetamide\$1) dmac) and (plasma non-plasma) and (dielectric\$1 osg organosilicate\$1 msq methylsilsesquioxane\$1 fsg fluor\$3 "silicate glass" sio2 (silicon same dioxide\$1))	US-PGPUB; USPAT	OR	ON	2008/08/25 11:08
S19	0	(pattern patterning) and (trench via) and "low-k" and (solvent acid (dimethyl same acetamide) dmac) and (plasma non-plasma) and (dielectric\$1 osg organosilicate msq methylsilsesquioxane fsg fluorine fluoride "silicate glass" sio2 (silicon same dioxide))	USOCR	OR	ON	2008/08/25 11:09
S20	136	S18 and "134".clas.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/25 11:10
S22	96	S20 and 134/ 1, 1.2,2,3, 19,26, 16,21,34,35,37.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/25 11:15
S23	79	S22 and photoresist\$1	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/25 11:16
S24	79	S23 and plasma	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/25 11:16
S25	36	S24 and (anneal\$4 bak\$4)	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/25 11:17
S26	0	S22 and S17	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/25 11:18
S27	11	pattern\$4 and (trench\$1 via\$1) and "low-k" and (solvent\$1 acid\$1 (dimethyl same acetamide\$1) dmac) and (plasma non-plasma) and (dielectric\$1 osg organosilicate\$1 msq methylsilsesquioxane\$1 fsg fluor\$3 "silicate glass" sio2 (silicon same dioxide\$1))	FPRS; EPO; JPO; DERWENT	OR	ON	2008/08/25 11:18
S28	47	S25 S27	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2008/08/25 11:18
S29	0	S28 and S17	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/25 11:22
S30	1	"20050045206".pn.	US-PGPUB	OR	ON	2008/08/25 11:28
S31	1	S30 and boil\$3	US-PGPUB	OR	ON	2008/08/25 11:28
S32	3	S17 and low-k	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/25 11:42
S33	9	S17 and dielectric	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/25 11:44
S34	1	"5643407".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/25 11:47
S35	0	S34 and dielectric same low	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/25 11:47
S36	0	S34 and low-k	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/25 11:47
S37	0	S34 and capacit\$5	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/25 11:58
S38	1	"6100183".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/25 12:03
S39	1	S38 and (anneal\$4 bak\$4)	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/25 12:03

S40	47	S28 and low-k	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2008/08/25 12:16
S41	37	S40 and (anneal\$4 bak\$4)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2008/08/25 12:17

8/ 25/ 2008 6:14:13 PM

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